

## APPENDIX SHOWING MARKUPS OF AMENDMENTS

### IN THE SPECIFICATION:

Page 1, after the title and prior to the background section, add the paragraph:

This application is a divisional of application 09/825,418, filed 3 April 2001, a Convention application based on Japanese applications 101756 and 101765, both filed 4 April 2000.

### IN THE CLAIMS:

Cancel claims 1-18.

19. (Amended.) A wiring board, comprising:

a board of at least one layer comprising a conductor part, said conductor part comprising at least one of ground patterns or conductor patterns deployed on one surface of said board, or comprises a ground surface deployed over the entirety of one surface of said board, and at least a part of said conductor is formed by an electrically conductive magnetic thin film; and magnetic thin films deployed at least on part of said board or said conductor part.

Cancel claims 20-21.